

Title (en)
Injection-molded article

Title (de)
Spritzgussformteil

Title (fr)
Pièce de fonderie sous pression

Publication
EP 1253675 A3 20040908 (DE)

Application
EP 02008787 A 20020419

Priority
DE 10120362 A 20010426

Abstract (en)
[origin: EP1253675A2] The device has at least one inserted and molded-in electrical contact element and forms the wall part of an electrical or electronic device, e.g. an at least partial outer wall in the form of a housing or housing part (10) of the device or an at least partial inner wall in the form of a separating wall or intermediate floor of the device.

IPC 1-7
H01R 13/405

IPC 8 full level
H01R 13/405 (2006.01)

CPC (source: EP US)
H01R 13/405 (2013.01 - EP US); **H01R 2201/06** (2013.01 - EP US)

Citation (search report)
• [X] DE 4224720 A1 19940203 - DUERRWAECHTER E DR DODUCO [DE]
• [X] EP 0966075 A1 19991222 - SUMITOMO WIRING SYSTEMS [JP]
• [X] DE 19963705 A1 20000817 - AISIN AW CO [JP], et al

Designated contracting state (EPC)
AT BE CH CY DE DK ES FI FR GB GR IE IT LI LU MC NL PT SE TR

DOCDB simple family (publication)
EP 1253675 A2 20021030; EP 1253675 A3 20040908; EP 1253675 B1 20070606; AT E364242 T1 20070615; CY 1106687 T1 20120523; DE 10120362 A1 20021121; DE 50210257 D1 20070719; DK 1253675 T3 20070702; ES 2284742 T3 20071116; PT 1253675 E 20070622; US 2002164904 A1 20021107; US 6840821 B2 20050111

DOCDB simple family (application)
EP 02008787 A 20020419; AT 02008787 T 20020419; CY 071100862 T 20070702; DE 10120362 A 20010426; DE 50210257 T 20020419; DK 02008787 T 20020419; ES 02008787 T 20020419; PT 02008787 T 20020419; US 13274002 A 20020426